

Recommendation & Guideline Values for storage conditions for bare PCBs

(all settings of parameters are subject to customized processing procedures)

Target:

- Action instructions to assure soldering process for bare PCBs
- Prevention against mechanical damage and reduction of solderability

Methods:

- Definition of storage temperature and – relative humidity
- Storage in defined packing type/ packing foil

Recommendation for parameters:

- Storage temperature max. 30°C;
- relative humidity max. 70%
- package in nailed shrink foil (PE-Foil), coated vacuum foil (vacuum bag), antistatic
- optional: humidity indicators, desiccant in vacuum package
- optional: supportive plate (single, double sided)

(see also Recommendation & Guideline Values „drying before soldering “ for bare PCBs)